

SEMICONDUCTOR PACKAGE

ABSTRACT OF THE DISCLOSURE

A semiconductor package with a flash-proof device is proposed, in which at
5 least one chip and at least one passive device mounted on a substrate are covered by
a flash-proof device dimensionally designed for positioning the substrate in a
conventional mold and preventing a molding resin from flashing on the substrate in a
molding process, and thus quality of the fabricated package can be assured. Due to
no need of a specifically designed mold, fabrication costs are reduced. Furthermore,
10 the flash-proof device has its top side exposed to outside of an encapsulant formed in
the molding process, thereby allowing heat dissipating efficiency to be improved.
Moreover, the flash-proof device provides shielding for the chip and the passive
device received therein, so that external electromagnetic interference with
performance of the semiconductor package can be reduced.

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